TRADEMARK ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	Reassignment and Release of Security Interest

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
COMERICA BANK, successor by merger to Comerica Bank-California		06/21/2005	Michigan banking corporation:

RECEIVING PARTY DATA

Name:	SCP IP, INC.
Street Address:	400 BENJAMIN LANE
City:	BOISE
State/Country:	IDAHO
Postal Code:	83704
Entity Type:	CORPORATION: DELAWARE

PROPERTY NUMBERS Total: 5

Property Type	Number	Word Mark
Registration Number:	2648048	BARRACUDA
Serial Number:	76218315	TRITON
Registration Number:	2630279	ECO-PLATE
Registration Number:	2558579	KRONOS
Registration Number:	1984802	MARANGONI

CH $140.00 2648048

CORRESPONDENCE DATA

Fax Number: (858)677-1401
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Phone: 858-638-6717
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Correspondent Name: Erin O'Brien
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Address Line 2: Suite 1100
Address Line 4: San Diego, CALIFORNIA 92121

NAME OF SUBMITTER:	Erin O'Brien
Signature:	/Erin O'Brien/
Date:	06/23/2005

Total Attachments: 8
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REASSIGNMENT AND RELEASE OF SECURITY INTEREST

This Reassignment and Release of Security Interest is made as of June 21, 2005 by COMERICA BANK, successor by merger to COMERICA BANK-CALIFORNIA ("LENDER") to SCP IP, INC., a Delaware corporation, with its principal place of business at 400 Benjamin Lane, Boise, ID 83704 ("COMPANY").

Recital

WHEREAS, COMPANY assigned certain interests in the patents and trademarks listed on Exhibits A and B attached hereto (respectively, the "Patents" and the "Trademarks"), to LENDER under an Intellectual Property Security Agreement dated as of March 14, 2003. Lender's security interest in the Patents was recorded with the U.S. Patent and Trademark Office ("PTO") on November 18, 203 at Reel Number 014699 and Frame Number 0492. Lender's security interest in the Trademarks was recorded with the PTO on November 19, 2003 at Reel Number 002866 and Frame Number 0750.

WHEREAS, LENDER and COMPANY have entered into that certain First Amendment to Third Party Security Agreement, dated as of the date hereof, whereby LENDER agrees to release all interest that LENDER may have in the Patents and Trademarks.

Agreement

Now therefore, LENDER agrees that it releases its security interest in the Patents and Trademarks and reassigns to COMPANY, without warranty or recourse, all interest of LENDER in the Patents and Trademarks.

LENDER:

COMERICA BANK,
Successor by merger to Comerica Bank-California

Signature

Name: Rory James C

Title: Vice President

Address: 2321 Rosecrans Ave., Suite 5000
El Segundo, CA 90245

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EXHIBIT A

Patents

Prov./ U.S. Serial App. Numbers	Publication Number	Abbreviated Title	Full Title	Priority Date (Provisional Filing Date)	Date Filed	Inventor(s)
09/478,094		Surfactant Clean	Method for Reducing Particle Contamination During the Wet Processing of Semiconductor Substrates	01/05/99	01/05/00	Verhaverbeke
60/135,267 09/574,790		Copper Cleaning with SC1/HF	Method for Wet Processing Electronic Components Having Copper Containing Surfaces	05/21/99	05/19/00	Verhaverbeke
60/168,487 09/727/661	US-2002-0066717-A1 on 6/6/2002	Ozone Apparatus	Apparatus for Providing Ozonated Process Fluid and Methods for Using Same	12/02/99	12/01/00	Verhaverbeke & DiBello
09/930,009	US-2002-0104552-A1	Injection Tube Calibration	Systems and Methods for Forming Processing Streams	08/17/00	08/15/01	Kaiser & Bay
60/270,815 10/074,516	US-2002-0119245-A1	Etching of Ta and TaN	Method for Etching Electronic Components Containing Tantalum	02/23/01		Verhaverbeke
		Point of Use Chemical Generation with Gases				Walter
10/163,441 Prv'l was 60/295,919	confirm No. 6959	Colorimetric Sulfuric Monitoring	Method and Systems for Monitoring Process Fluids	06/05/01	06/05/01	DiBello, Carter & Bowen
10/301,322		Improved Low Pressure IPA Drying	Apparatus and Methods for Drying Electronic Component Precursors		11/21/01	DiBello
10/299,308		PTFE Meg Carrier	Sonic Transducers bonded with Polymers and Methods of Making Same for Efficient Sonic Energy Transfer	11/19/01	11/19/01	Gottschalk and Hollweck
		Reduced Volume Clean	Systems and Methods for Cleaning Semiconductor Substrates Using a Reduced Volume of Liquid	03/11/02		Savas, Zajac, and Galewski

	U.S. Patent Number	Appl Number	Full Title	Date Filed	Date Issued	Date of Expiration	Inventor(s)
1	4,577,650	612,355	Vessel and System for Treating Wafers with Fluids	05/21/84	03/25/86	03/25/03	McConnell
2	4,633,893	747,894	Apparatus for Treating Semiconductor Wafers	06/24/85	01/06/87	01/06/04	McConnell & Walter
3	4,738,272	747,895	Vessel and System for Treating Wafers with Fluids	06/24/85	04/19/88	04/19/05	McConnell
4	4,740,249	922,882	Vessel and System for Treating Wafers with Fluids	10/24/86	04/26/88	04/26/05	McConnell
5	4,778,532	765,294	Process and Apparatus for Treating Wafers with Process Fluids	08/13/85	10/18/88	10/18/05	McConnell & Walter
6	4,795,497	805,203	Method and System for Fluid Treatment of Semiconductor Wafers	12/04/85	01/03/89	01/03/06	McConnell & Walter
7	4,856,544	07/125,245	Vessel and System for Treating Wafers with Fluids	11/25/87	08/15/89	08/15/06	McConnell
8	4,899,767	/283,465	Method and System for Fluid Treatment of Semiconductor Wafers	12/12/88	02/13/90	02/13/07	McConnell & Walter
9	4,911,761	07/184,544	Process and Apparatus for Drying Surfaces	04/20/88	03/27/90	03/27/07	McConnell & Walter
10	4,917,123	07/252,823	Apparatus for Treating Wafers with Process Fluids	10/03/88	04/17/90	04/17/07	McConnell & Walter
11	4,984,597	/431268	Apparatus for Rinsing and Drying Surfaces	11/03/89	01/15/91	01/15/08	McConnell & Walter
12	5,383,484	08/093,116	Static Megasonic Cleaning System for Cleaning Objects	07/16/93	01/24/95	07/16/13	Thomas, Carolin, Erhardt & McConnell
13	5,972,123	09/096,898	Methods for Treating Semiconductor Wafers	06/12/98	10/26/99	06/12/18	Verhaverbeke
14	6,032,682	08/881,267	Method for Sulfuric Acid Resist Stripping	06/24/97	03/07/00	06/24/17	Verhaverbeke
15	6,132,522	08/684,543	Wet Processing Methods for the Manufacture of Electronic Components Using Sequential Chemical Processing	07/19/96	10/17/00	07/19/16	Verhaverbeke, McConnell & Trissel
16	6,143,087	09/253,629	Methods for Treating Objects	02/19/99	11/07/00	02/19/19	Walter
17	6,165,912	09/395,398	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel	09/14/99	12/26/00	09/14/19	McConnell & Verhaverbeke
18	6,245,158 B1	09/324,813	Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperatures	06/02/99	06/12/01	06/19/19	Verhaverbeke
19	6,261,845 B1	09/257,488	Method and Systems for Determining Chemical Concentrations and Controlling the Processing of Semiconductor Substrates	02/25/99	07/17/01	02/25/19	Verhaverbeke, DiBello & McConnell
20	6,348,101	09/669/789	Methods for Treating Objects	09/26/00	02/19/02	09/26/20	Walter
21	6,378,544 B1	60/130,466 09/564,358	Pressure Relief Device and Method of Using the Same	04/22/99	04/30/02	04/22/19	DiBello
22	6,491,763	09/805,348	Process and Apparatus for Treating Electronic Components	03/13/01	12/10/02	03/13/21	Verherbeke, Liu, Walter, Sheen& McConnell
23	6,495,099	09/209,101	Wet Processing Methods for the Manufacture of Electronic Components	12/10/98	12/17/02	12/10/18	Verhaverbeke & McConnell

FOREIGN PATENTS

US Patent Number	Foreign App. Serial Number	Publication Number	Abbreviated Title	Full Title	Country Filed	Priority Date	Date Filed	Inventor(s)
6,261,845 B1	92922583.7		Methods for Treating Objects	Ultra Cleaning of Involuted Microparts	Europe	12/17/93	10/02/92	Walter
6,261,845 B1	98 20 3334.2			Method for Treating Objects	Europe	10/04/91	10/02/98	Walter
6,132,522	PCT/US97/1208 8 WO98/03273		No Rinse / Sequential Processing	Wet Processing Methods for the Manufacture of Electronic Components Using Sequential Chemical Processing	PCT	07/19/96	07/14/97	Verhaverbeke, McConnell & Trissel
6,132,522	97932574.3 97936936027.0 Pub.No. 0912259		No Rinse / Sequential Processing	Wet Processing Methods for the Manufacture of Electronic Components Using Sequential Chemical Processing	EPO	07/19/96	07/14/97	Verhaverbeke, McConnell &Trissel
6,132,522	10-1999-7000355		No Rinse / Sequential Processing	Wet Processing Methods for the Manufacture of Electronic Components Using Sequential Chemical Processing	Korea	07/19/96	07/14/97	Verhaverbeke, McConnell &Trissel
6,132,522	507004/98		No Rinse / Sequential Processing	Wet Processing Methods for the Manufacture of Electronic Components Using Sequential Chemical Processing	Japan	07/19/96	07/14/97	Verhaverbeke, McConnell & Trissel
5,972,123	PCT/US98/1231 0 WO98/56726		Co-injection of Buffered HF/ BOE	Methods for Treating Semiconductor Wafers	PCT	06/13/97	06/12/98	Verhaverbeke
5,972,123	98929046.5 Pub. No. 0989962		Co-injection of Buffered HF/ BOE	Methods for Treating Semiconductor Wafers	EPO	06/13/97	06/12/98	Verhaverbeke
5,972,123	98805967.3 Pub.No.CN1259 925A		Co-injection of Buffered HF/ BOE	Methods for Treating Semiconductor Wafers	China	06/13/97	06/12/98	Verhaverbeke
5,972,123	503284/99		Co-injection of Buffered HF/ BOE	Methods for Treating Semiconductor Wafers	Japan	06/13/97	06/12/98	Verhaverbeke
5,972,123	99-7010670		Co-injection of Buffered HF/ BOE	Methods for Treating Semiconductor Wafers	Korea	06/13/97	06/12/98	Verhaverbeke
09/209,101	PCT/US98/2611 8 WO99/30355		Direct to Dry	Wet Processing Methods for the Manufacture of Electronic Components	PCT	12/11/97	12/09/99	Verhaverbeke & McConnell
09/209,101	87120411		Direct to Dry	Wet Processing Methods for the Manufacture of Electronic Components	Taiwan	12/11/97	12/09/98	Verhaverbeke & McConnell
09/209,101	98 8 08586.0 CN 1268244A		Direct to Dry	Wet Processing Methods for the Manufacture of Electronic Components	China	12/11/97	12/09/98	Verhaverbeke & McConnell
09/209,101	98962020.8 Pub. No. 1044465		Direct to Dry	Wet Processing Methods for the Manufacture of Electronic Components	EPO	12/11/97	12/09/98	Verhaverbeke & McConnell
09/209,101	524813/00		Direct to Dry	Wet Processing Methods for the Manufacture of Electronic Components	Japan	12/11/97	12/09/98	Verhaverbeke & McConnell
09/209,101	2000-7005687		Direct to Dry	Wet Processing Methods for the Manufacture of Electronic Components	Korea	12/11/97	12/01/98	Verhaverbeke & McConnell
09/324,813	PCT/US99/1214 4 WO99/62837		Cool Rinsing	Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperature	PCT	06/02/98	06/02/99	Verhaverbeke
09/324,813	99 8 06667.2		Cool Rinsing	Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperature	China	06/02/98	06/02/99	Verhaverbeke
09/324,813	99926113.4 Pub. No. 1082271		Cool Rinsing	Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperature	EPO	06/02/98	06/02/99	Verhaverbeke
09/324,813	PCT/US99/1214 4 552055/00		Cool Rinsing	Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying	Japan	06/02/98	06/02/99	Verhaverbeke

US Patent Number	Foreign App. Serial Number	Publication Number	Abbreviated Title	Full Title	Country Filed	Priority Date	Date Filed	Inventor(s)
				Temperature				
6,378,544 B1	PCT/US00/10590 WO 00/65266		Rupture Disks	Pressure Relief Device and Method of Using the Same	PCT	04/22/99	04/20/00	DiBello
6,378,544 B1	2001-7013323		Rupture Disks	Pressure Relief Device and Method of Using the Same	Korea	04/22/99	04/20/00	DiBello
6,378,544 B1	89107537		Rupture Disks	Pressure Relief Device and Method of Using the Same	Taiwan	04/22/99	04/21/00	DiBello
6,378,544 B1	928225.2		Rupture Disks	Pressure Relief Device and Method of Using the Same	Europe	04/23/99	04/22/00	DiBello
6,378,544 B1	613970/00		Rupture Disks	Pressure Relief Device and Method of Using the Same	Japan	04/22/99	04/20/00	DiBello
6,378,544 B1	806473.3		Rupture Disks	Pressure Relief Device and Method of Using the Same	China	04/22/99	10/19/01	DiBello
09/395,398	PCT/US99/21339 WO 00/15352		Electroless Copper Deposition	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel	PCT	09/17/98	09/16/99	Verhaverbeke & McConnell
09/395,398	PCT/US99/21339 WO 00/15352 SN# 99 8 10935.5		Electroless Copper Deposition	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel	China	09/14/99	3/ /01	Verhaverbeke & McConnell
09/395,398	99969047.2 Pub No 1115503		Electroless Copper Deposition	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel	EPO	09/14/99	09/16/99	Verhaverbeke & McConnell
09/395,398	569928/00		Electroless Copper Deposition	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel	Japan	09/14/99	3/ /01	Verhaverbeke & McConnell
09/395,398	PCT/US99/21339 WO 00/15352		Electroless Copper Deposition	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel	Korea	09/14/99	3/ /01	Verhaverbeke & McConnell
60/135,267	PCT/US00/14019	1198620	Copper Cleaning	Methods for Wet Processing Electronic Components Having Copper Containing Surfaces	PCT	05/21/99	05/19/00	Verhaverbeke
60/135,267	936165		Copper Cleaning	Methods for Wet Processing Electronic Components Having Copper Containing Surfaces	EPO			Verhaverbeke
60/135,267	00807855.6	CN 1352703A No. 23 Vol 18 patent gazette	Copper Cleaning	Methods for Wet Processing Electronic Components Having Copper Containing Surfaces	China	05/21/99	11/21/01	Verhaverbeke
60/135,267	620153/00		Copper Cleaning	Methods for Wet Processing Electronic Components Having Copper Containing Surfaces	Japan	05/21/99	05/19/00	Verhaverbeke
	2001-7014820		Copper Cleaning	Methods for Wet Processing Electronic Components Having Copper Containing Surfaces	Korea	05/21/99	05/19/00	Verhaverbeke
60/168,487	PCT/US00/42449 Pub#WO 01/40124		Ozone Apparatus	Apparatus for Providing Ozonated Process Fluid and Methods for Using Same	PCT	12/02/99	12/01/00	Verhaverbeke & DiBello
60/168,487	89125686		Ozone Apparatus	Apparatus for Providing Ozonated Process Fluid and Methods for Using Same	Taiwan	12/02/99	12/02/00	Verhaverbeke & DiBello
60/188,895	PCT/US01/07959		IPOZONIA	Processes and Apparatus for Treating Electronic Components	PCT	03/13/00	03/13/01	Verhaverbeke, Liu, Walter, Sheen & McConnell
60/188,895	90105810		IPOZONIA	Processes and Apparatus for Treating Electronic Components	Taiwan	03/13/00	03/13/01	Verhaverbeke, Liu, Walter, Sheen & McConnell
60/270,815	CFMT-0280		Etching of Ta and TaN	Method for Etching Electronic Components Containing Tantalum	Taiwan	02/23/01		Verhaverbeke
60/270,815	PCT/US02/04299		Etching of Ta and TaN	Method for Etching Electronic Components Containing Tantalum	PCT	02/23/01		Verhaverbeke
09/930,009	90120208		Injection Tube Calibration	Systems and Methods for Forming Processing Streams	Taiwan	08/17/00	08/15/01	Kaiser& Bay
09/930,009	PCT/US01/41720		Injection Tube Calibration	Systems and Methods for	PCT	08/17/00	08/15/01	Kaiser & Bay

US Patent Number	Foreign App. Serial Number	Publication Number	Abbreviated Title	Full Title	Country Filed	Priority Date	Date Filed	Inventor(s)
	9			Forming Processing Streams				
60/295,919	PCT/US02/17703		Chemical End Life Monitoring	Methods and Systems for Monitoring Process Fluids	PCT	Method and Systems for Monitoring Process Fluids	06/04/02	DiBello, Carter & Bowen
60/295,919			Chemical End Life Monitoring	Methods and Systems for Monitoring Process Fluids	Taiwan	Method and Systems for Monitoring Process Fluids	06/04/02	DiBello, Carter & Bowen

EXHIBIT B

Trademarks

Registration No.	Filing Date	Date of Registration	State/ Country	Trademark	Classification
2 079 255	06/08/94	09/27/94	DE	**MARANGONI**	Kl.:9,11,37
634 428	12/08/94	05/22/95	IR: AT, BX CH/LI ES,FR,IT MC,PT,CN		Kl.: 7, 37
6 107 1996	11/15/94	11/01/96	DK		Kl.: 11, 37
2001646	11/03/94	09/15/95	GB		Kl.:7,11,37
167 065	11/08/94	07/09/96	IE		Klasse: 7
167 066	06/08/94	07/09/96	IE		Klasse: 11
202 498	09/17/96	01/15/99	IE		Klasse: 37
121971	12/07/94	10/17/98	GR		Kl.: 7,11,37
4 296 323	12/07/94	07/16/99	JP		Klasse: 7
4 348 172	12/07/94	12/24/99	JP		Klasse: 7
4101041	12/07/94	01/09/98	JP		Klasse: 37
1,984,802	12/05/94	07/02/96	US		Kl.: 7, 37
692094	11/10/94	10/01/95	TW		Klasse: 7
330534	11/10/94	12/28/95	KR		Klasse: 38
337867	11/10/94	04/23/96	KR		Klasse: 39
32654	11/10/94	08/13/96	KR		Klasse:112
374433	10/23/95	02/21/97	ID		Klasse: 7
363996	10/23/95	02/21/97	ID		Klasse: 11
374432	10/23/95	02/21/97	ID		Klasse: 37
10842 / 95	10/12/95	In examination	MY		Klasse: 7
10845 / 95	10/12/95	06/13/98	MY		Klasse: 11
18314/97	12/01/97	In examination	MY		Klasse: 37
Kor68679	01/29/96	02/20/98	TH		Klasse: 7
Bor9942	01/29/96	04/21/00	TH		Klasse: 37
399 80 741	12/20/99	01/20/00	DE	**BARRACUDA**	Class: 7, 11, 42
743 387	06/20/00	11/09/00	IR: BX, FR IT, GB		Class: 7, 11, 42
68 107	06/19/00	In examination	JP		Class: 7
4 455 910	06/19/00	02/23/01	JP		Class:37
4 455 911	06/19/00	02/23/01	JP		Class: 42
3008 / 2000	06/20/00	In examination	KR		
89038352	07/05/00	In examination	TW		Class: 7
89038353	07/05/00	In examination	TW		Class: 11
89038354	07/05/00	In examination	TW		Class: 37
90 005 639	02/22/01	In examination	TW		Class 42
76/075,632	06/20/00	In examination	US		Class: 7, 11, 37
300 36 246	05/12/00	10/05/00	DE	**ECO-Plate**	Class 7, 9, 37
756 305	11/10/00	In examination	IR: BX, FR,IT GB,AT,JP		Class 7,37
5403/2000	11/10/00	In examination	KR		Class 9,37
890 708 70	12/08/00	In examination	TW		Class 7
890 708 71	12/08/00	In examination	TW		Class 9
890 708 72	12/08/00	In examination	TW		Class 37
76/162,598	11/09/00	In examination	US		Class 7,37
300 65 241	08/31/00	11/27/00	DE	**Triton**	Class: 7, 11, 37
755 867	02/23/01	05/24/01	IR: BX, FR, IT GB,JP		Class 7,11, 37
710/2001	02/26/01	In examination	KR		Class 7,37
90 006 121	02/26/01	In examination	TW		Class 7
90 006 122	02/26/01	In examination	TW		Class 11

Registration No.	Filing Date	Date of Registration	State/ Country	Trademark	Classification
90 006 123	02/26/01	In examination	TW		Class 37
76/218,315	02/28/01	In examination	US		Class 7,11,37
300 84 582	11/17/00	12/19/00	DE	**KRONOS**	Class: 7, 11, 37
not known yet			IR: BX, FR, IT GB,JP		Class 7,11, 37
1075/2001	03/26/01	In examination	KR		Class 7,37
90 006 904	03/20/01	In examination	TW		Class 7
90 006 905	03/20/01	In examination	TW		Class 11
90 006 906	03/20/01	In examination	TW		Class 37
76/236,977	04/04/01	In examination	US		Class 7,11,37

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